



Operation and performance of the CMS silicon tracker

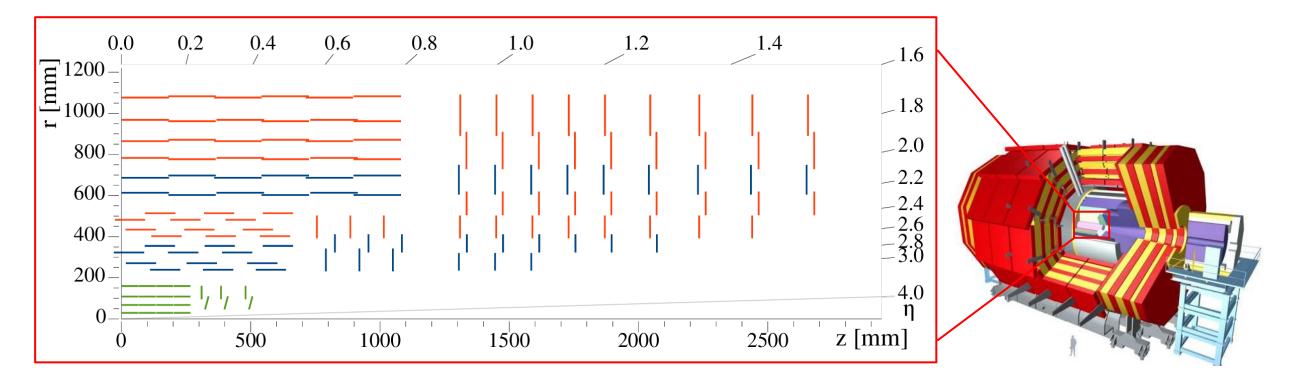
Erik Butz

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Overview of the CMS central silicon tracker

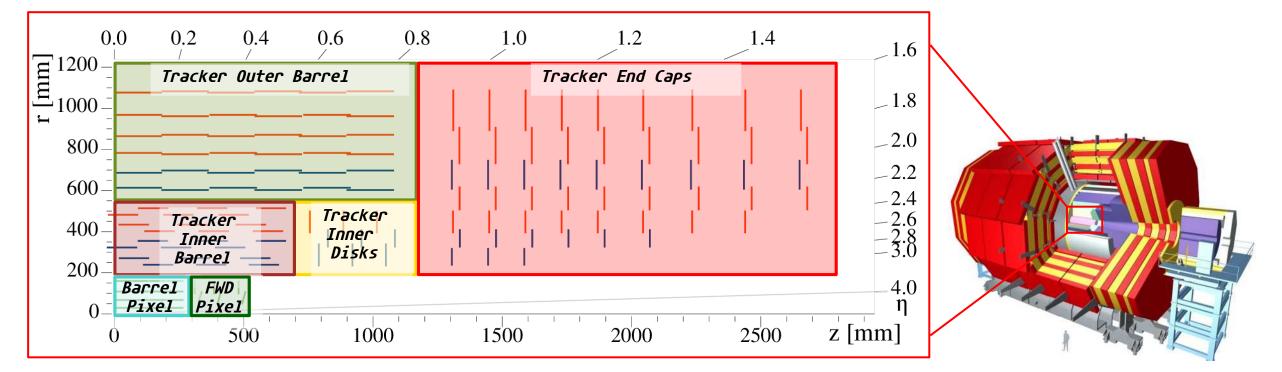




- All-silicon central tracking system
- 200 m² of active area, of which 1.75 m² pixel detector
- 5.6 m in length, 2.5 m diameter
- Innermost layer at 2.9 cm from beam line, outermost layer at ~110 cm
- Strip Tracker in place since end of 2007
- Pixel Detector completely replaced, Phase-1 upgrade, in 2016/17
 - Pixel detector designed to be removable and reinstallable quickly

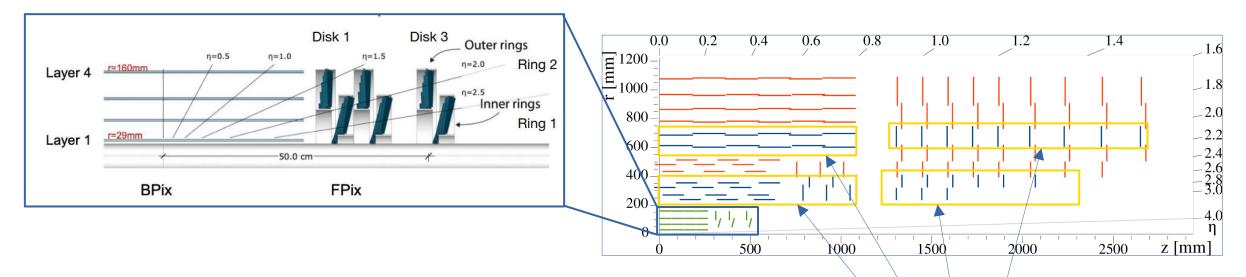
Overview of the CMS central silicon tracker



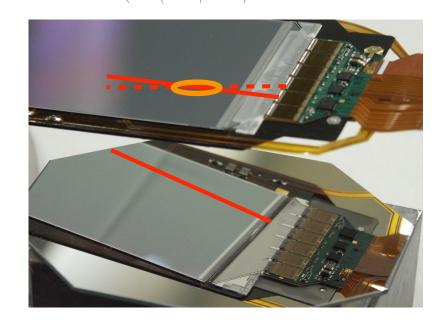


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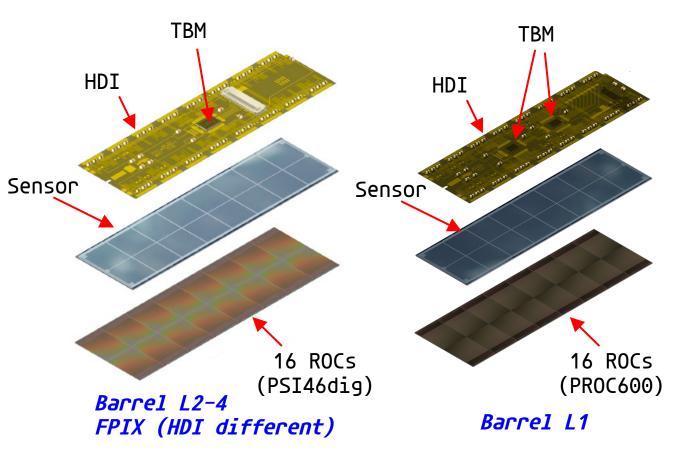
Overview of the CMS central silicon tracker



- 14 barrel layers: 4 pixel and 4+6 strip
- 15 forward disks: 3 pixel and 3+9 strip
- 1'856 pixel modules
 - module size about 1.5x6 cm²
 - 124M pixels with 100x150 μ m² size
- 15'148 Silicon Strip Modules
 - 9.3M microstrips, pitch 80 μm to 205 μm, length: 10-20 cm
 - 4 strip layers/3 rings have "stereo modules"
 - → modules mounted back-to-back with 100 mrad stereo angle



Pixel Detector – Modules

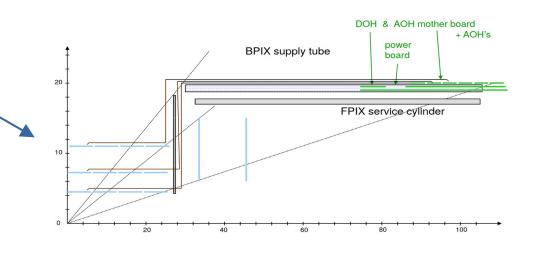




- **n-in-n silicon sensors**, double-sided processing, 285 µm active thickness
- Readout Chip (ROC):
 - -PSI46dig (BPIX L2-4, FPIX)
 - Efficiency > 90% up to 200 MHz/cm²

-PROC600 (BPIX L1)

- Efficiency > 90% up to 600 MHz/cm²
- Token-bit manager (TBM) ASIC to orchestrate readout
 - -2 TBMs for Layer 1 modules to cope with very high data rates
- Auxiliary electronics located **outside of tracking volume** on "service cylinder"
 - -electro-opto conversion
 - -DCDC converters
 - -delay chips



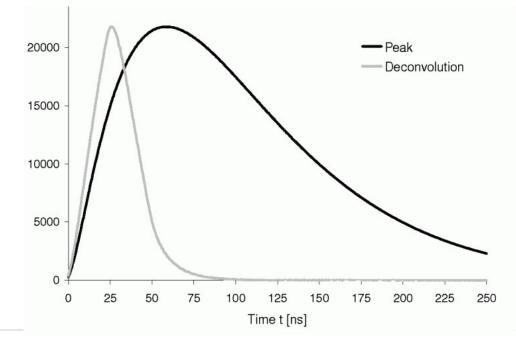
Strip Detector

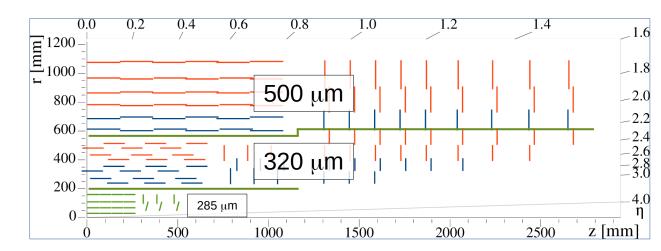
•Strip Modules

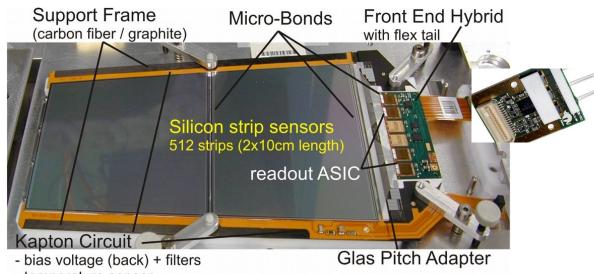
- -p-in-n sensors, single-sided processing
 - $\bullet 320~\mu m$ thickness in inner layers/rings
 - $\bullet 500~\mu m$ thickness in outer layers/rings
 - \rightarrow compensate for longer strip length in
 - outer layers \rightarrow **two sensors daisy-chained**
- analog opto-hybrid for electro-opto conversion in close proximity to individual modules

-APV25 readout chip

- Two readout modes:
 - -Peak mode (1 sample from CR-RC shaper, slow shaper \rightarrow **low power**)
 - -**Deconvolution** (3 sample weighted average on-chip
 - → shorter effective pulse shape)







- temperature sensor



Detector Status

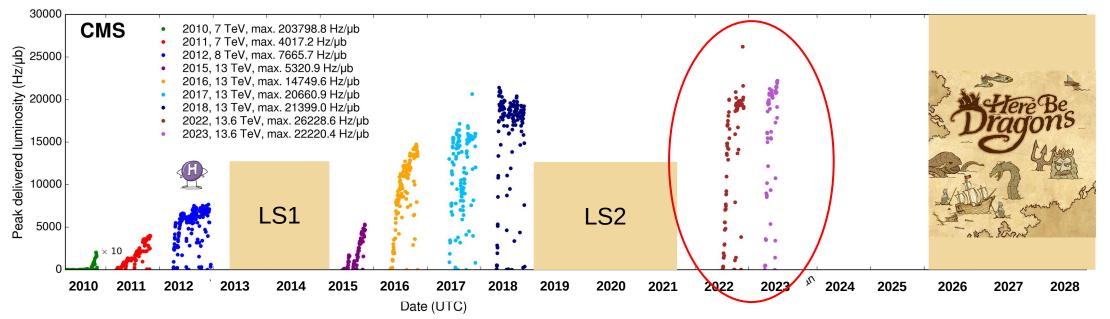
Data taking conditions in Run 3



Instantaneous luminosity

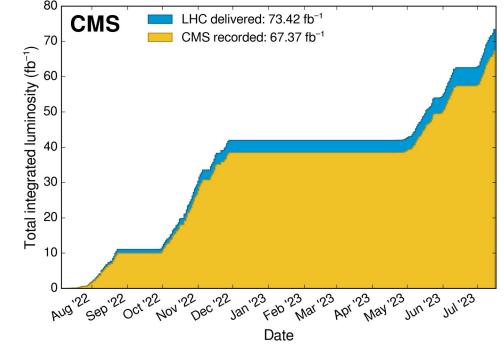
Data included from 2010-03-30 11:22 to 2023-07-16 23:02 UTC

The CMS Inner Tracker for the HL-LHC Upgrade A. Papadopoulos, Today 17:20 The CMS Outer Tracker for the HL-LHC Upgrade, N. Roewert, Today 17:40



- In 2022/2023 LHC running routinely at luminosities around 2x10³⁴ cm⁻¹s⁻¹
- Pile-up reaching up to 65 overlapping collisions at the start of LHC fills
- CMS recording data with around 92% efficiency
- Level-1 trigger rate up to 110 kHz

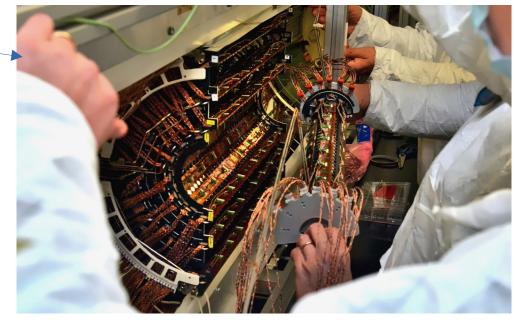




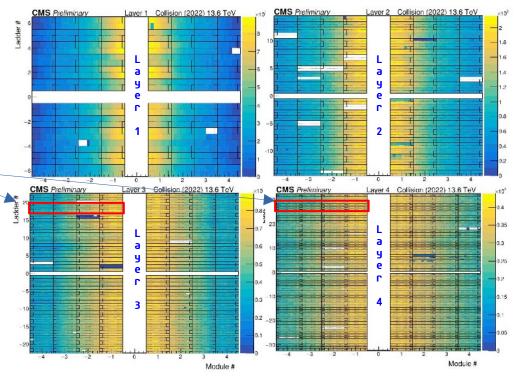
Pixel Detector – Operational Status

- Refurbishments during LS2
 - Completely new BPIX Layer 1 (exchange planned in any case due to radiation damage)
 - Opportunity used to develop and deploy improved version of ASICs (TBM and PROC600)
 - Full set of new DCDC converters
 - Other work during LS2
 - Replacement of few non-working modules in BPIX Layer 2
 - Rework of cooling connections on FPIX
 - Change of low and high voltage distribution for FPIX
 - Upgrade of power supplies
- Active fraction at beginning of June 2023
 - 98.4 % of Barrel Pixels
 - 97.9 % of Forward Pixels
- New failure in June 2023: group of 27 modules in Barrel layers 3/4 with problem in clock distribution
 - Excluded from data taking
 - \rightarrow Barrel Pixel ~96% active channels





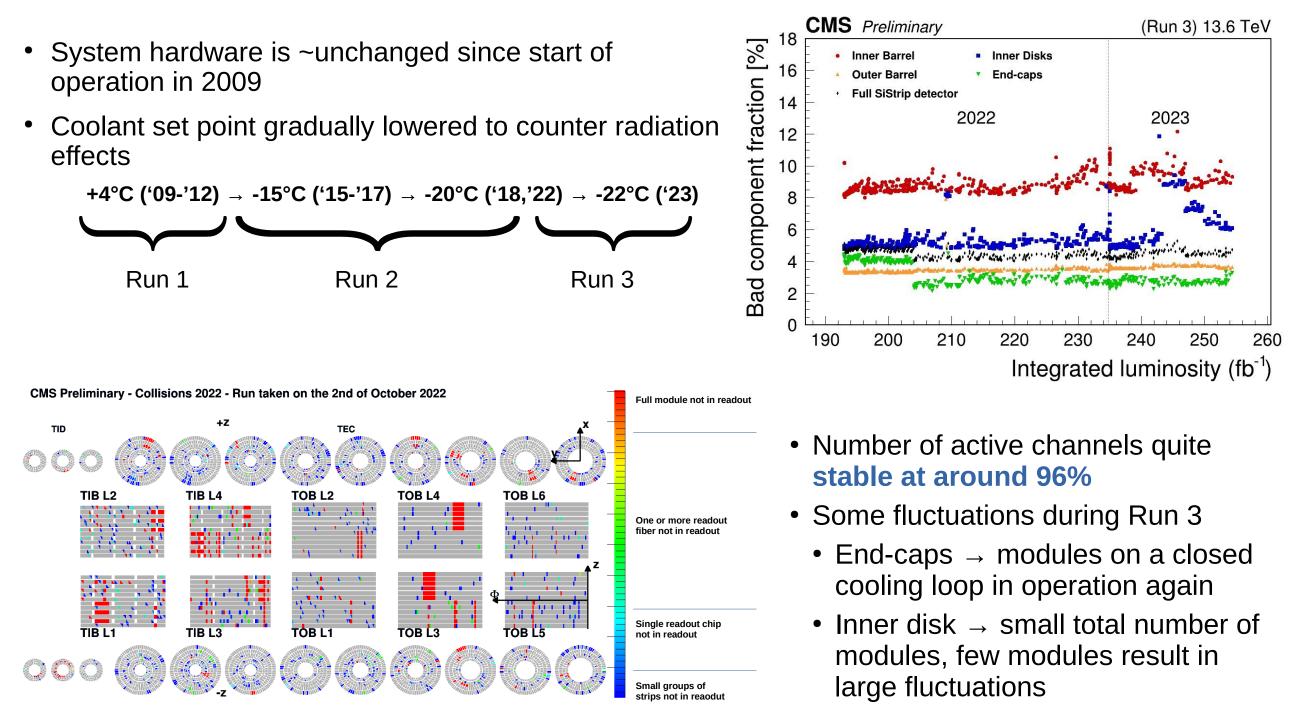
Installation of new BPIX Layer 1



Hit map for barrel layers

Strip Detector – Operational Status





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Detector Performance

Pixel – Cluster Charge



CMS Preliminary (Run 3) 13.6 TeV **CMS** Preliminary (Run 3) 13.6 TeV 25 35 Avg. norm. on-track clu. charge [ke] Avg. norm. on-trk clu. charge [ke] 2023 2023 2022 2022 Forward Pixel 24 30 Barrel Pixel 23 25 20 21 15 FPIX BPIX Disk 1 ---- Gain calibration 20 Disk 2 — Technical stop 10 Layer 1 — - Layer 1 HV change Disk 3 - Layer 2 ---- Gain calibration Disk -1 Mind --- Layer 3 --- Technical stop 19 🔶 Disk -2 Different 5 - Disk -3 🔫 Layer 4 y scale 10 20 30 40 50 20 40 10 30 50 Delivered integrated luminosity [fb⁻¹] Delivered integrated luminosity [fb⁻¹

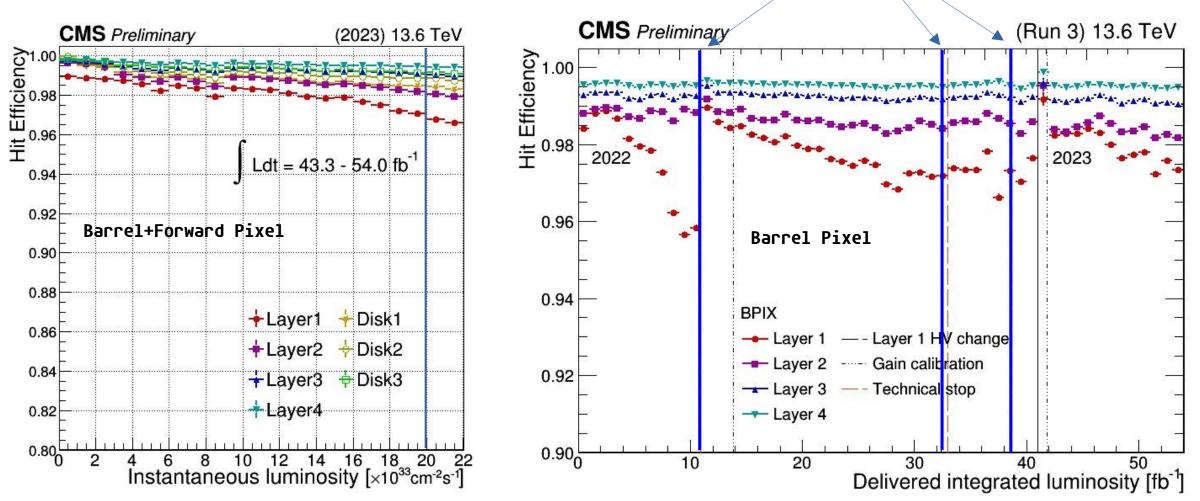
Layer 1 HV changes

- Rapid change of conditions in new BPIX layer $1 \rightarrow$ expected
 - Now pace of change has slowed, in line with other layers (see also later)
- Steep reduction initially for new layer 1 before HV change around 11 fb⁻¹ \rightarrow luminosity accumulated in short time

Pixel – Hit efficiency

Layer 1 HV changes

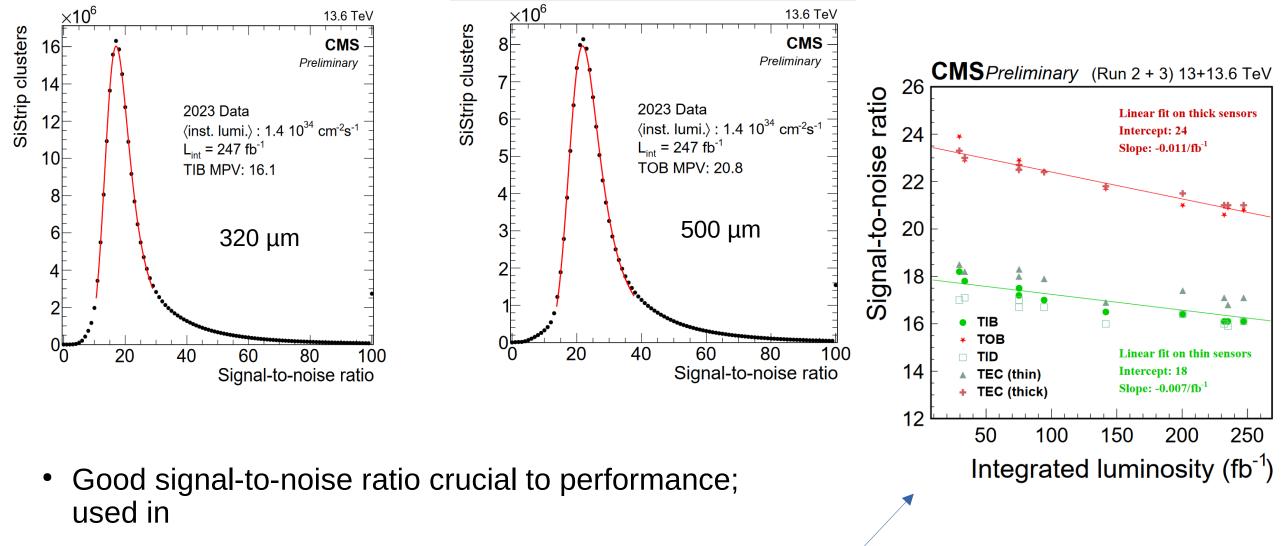




- As function of instantaneous luminosity and integrated luminosity
- Hit efficiency at 2x10³⁴cm⁻¹s⁻¹
 - above 98% for all BPIX L2-4 and FPIX,
 - BPIX L1 efficiency around 97%
- Sharp drop seen in cluster charge also seen in hit efficiency
 - Fully recovered after HV adjustment

Strips – Signal to Noise ratio

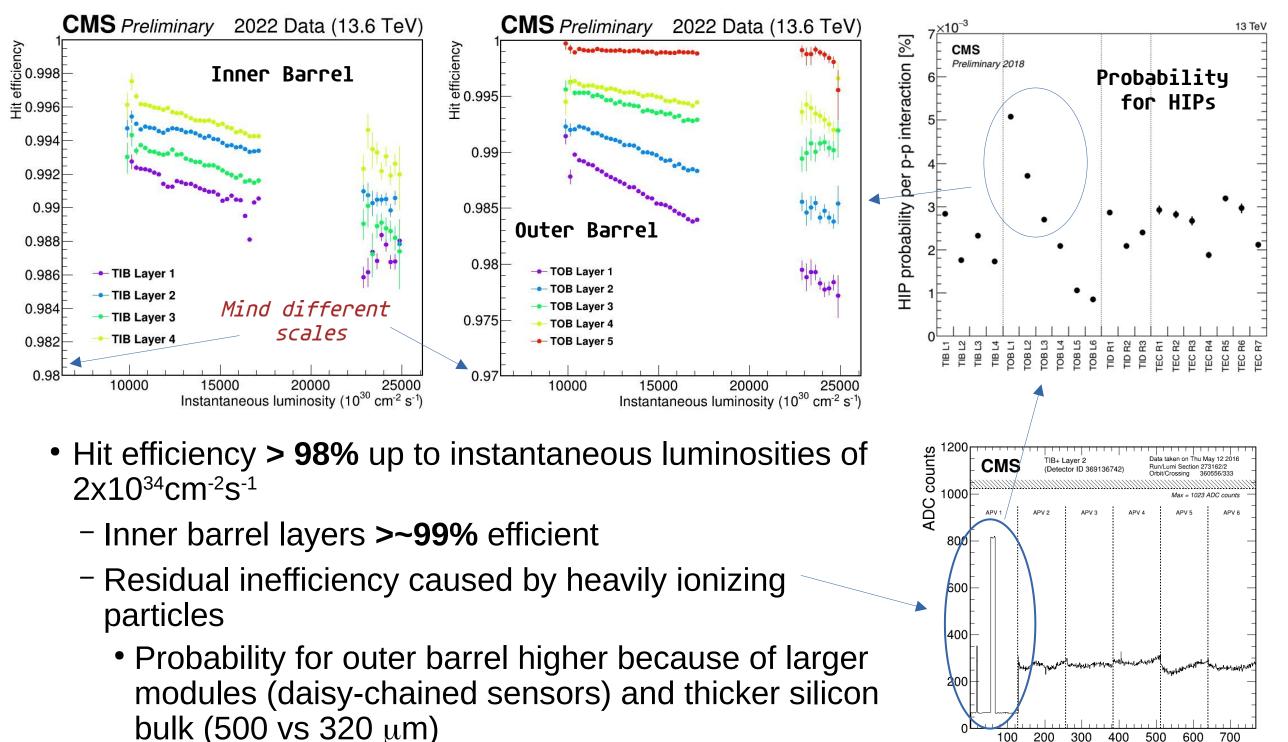




- Zero-suppression in readout electronics
- Offline cluster reconstruction
- Extrapolation to 500 fb-1 yields S/N > 14 (18) for thin (thick) sensors \rightarrow excellent result
 - Design specification of S/N > 10 after 10 years and 500 fb-1

Strips – Hit Efficiency

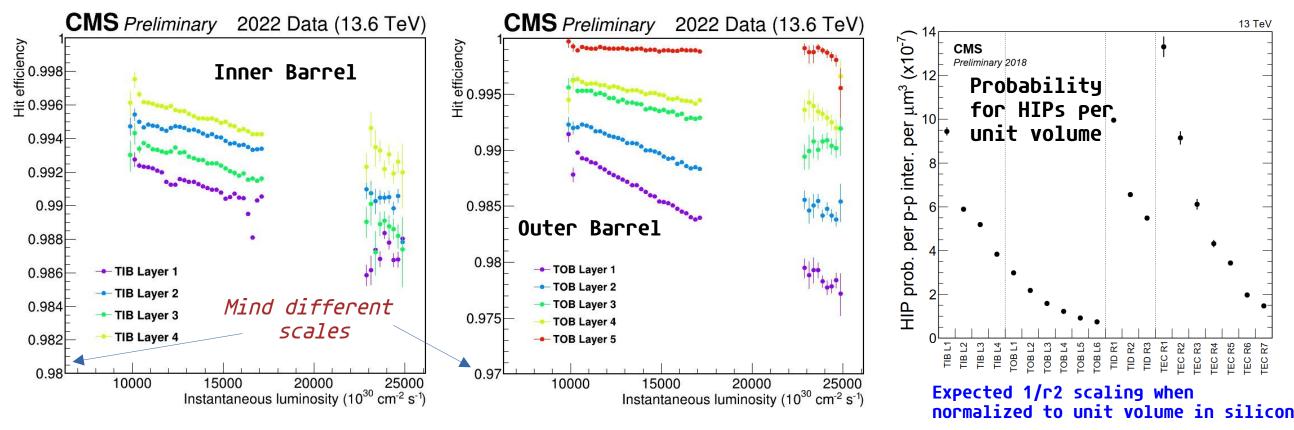




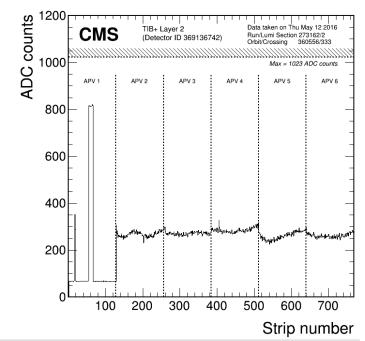
Strip number

Strips – Hit Efficiency





- Hit efficiency > 98% up to instantaneous luminosities of 2x10³⁴cm⁻²s⁻¹
 - Inner barrel layers >~99% efficient
 - Residual inefficiency caused by heavily ionizing particles
 - Probability for outer barrel higher because of larger modules (daisy-chained sensors) and thicker silicon bulk (500 vs 320 μm)

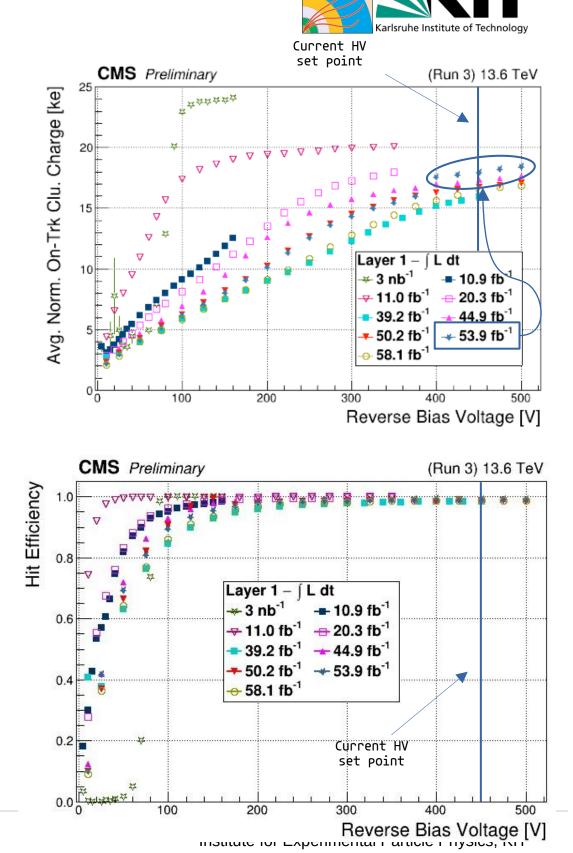




Radiation Effects

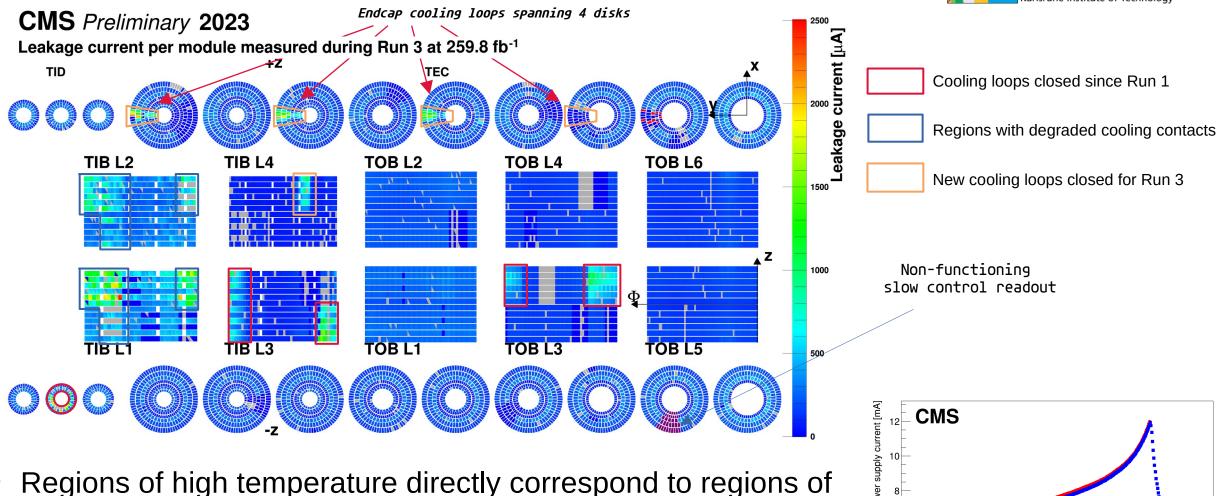
Barrel Pixel Layer 1 – Radiation effects

- Unirradiated sensors operated at 150 V
- n-in-n sensors went through type inversion very early in Run 3
- HV settings raised to keep efficiency and spatial resolution optimal
 - Current set point: 450 V
 - Maximum 800 V
 - underdepleted operation possible

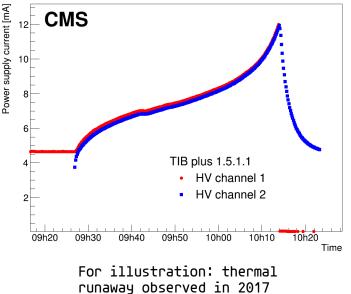


Strips – Sensor Leakage current



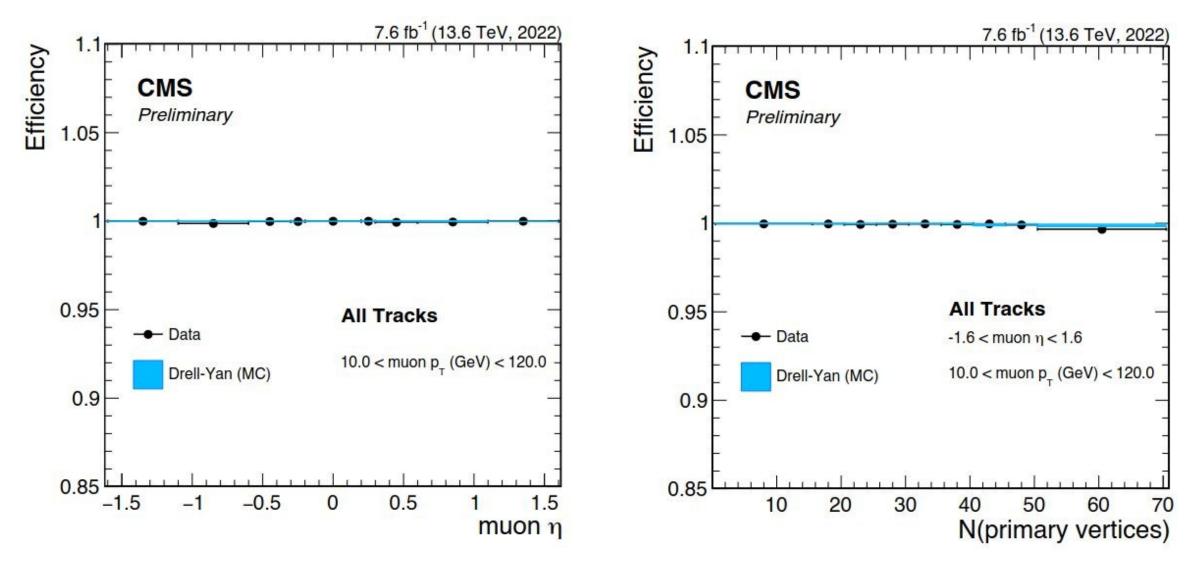


- Regions of high temperature directly correspond to regions of high leakage current
 - Individual modules in TIB layer 1 and 3 above 1 mA per module
 - Before end of Run 3 will hit power supply limit or thermal runaway on some detector parts
 - Mitigation possible through partial switch-off or lowering of bias voltage
- Vast majority of strip tracker at very low leakage currents



Summary (sort of...actually tracking performance)





• Efficiency measured with a tag-and-probe in $Z \rightarrow \mu\mu$ – Uses data from early Run 3 N.B. effect of BPIX L3/4 failure not in here but effect on efficiency small (but small increase in fake rate)

• Excellent tracking efficiency as function of η and #primary vertices

Summary and Outlook

- CMS all-silicon tracker continues to perform very well also after many years of operation
 - Active detector fraction above 95% for all detector parts
 - New failures in pixel (Layer 3 and 4 in one sector) and strips (2 additional closed cooling loops) have been encountered after LS2
 - Mitigation has been put in place where possible
- Performance parameters like signal height/signal-to-noise ratio, hit efficiency and hit resolution continue to be excellent
- Outlook until end-of-life at start of LS3 indicates good margin for excellent performance for both systems





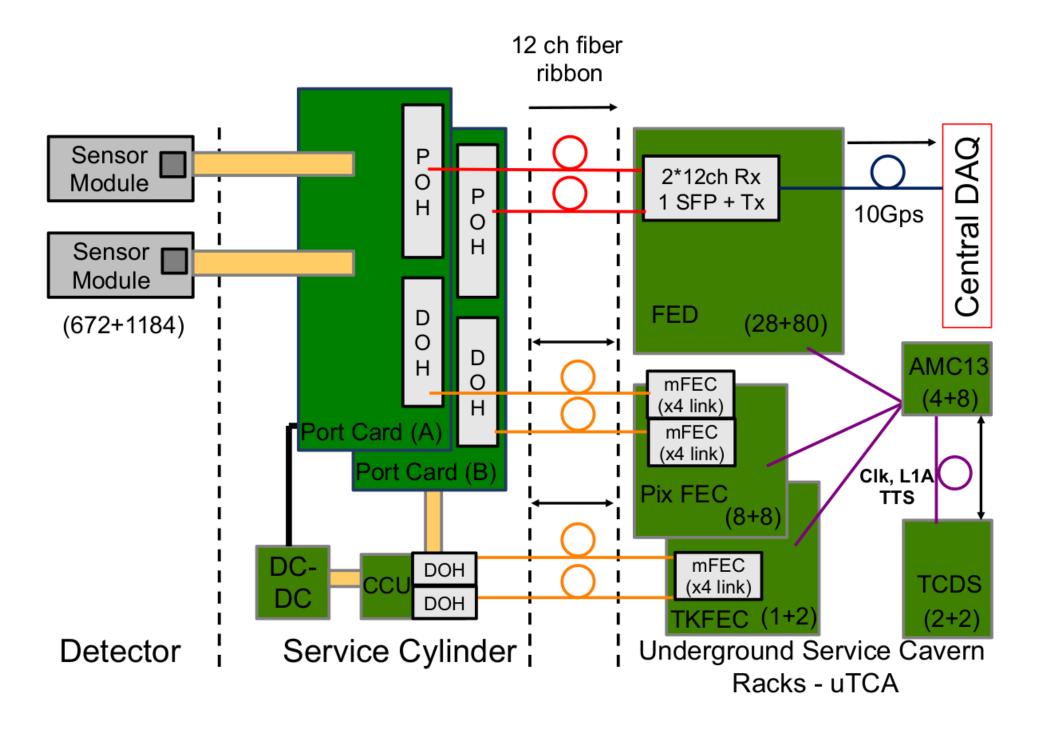


Backup

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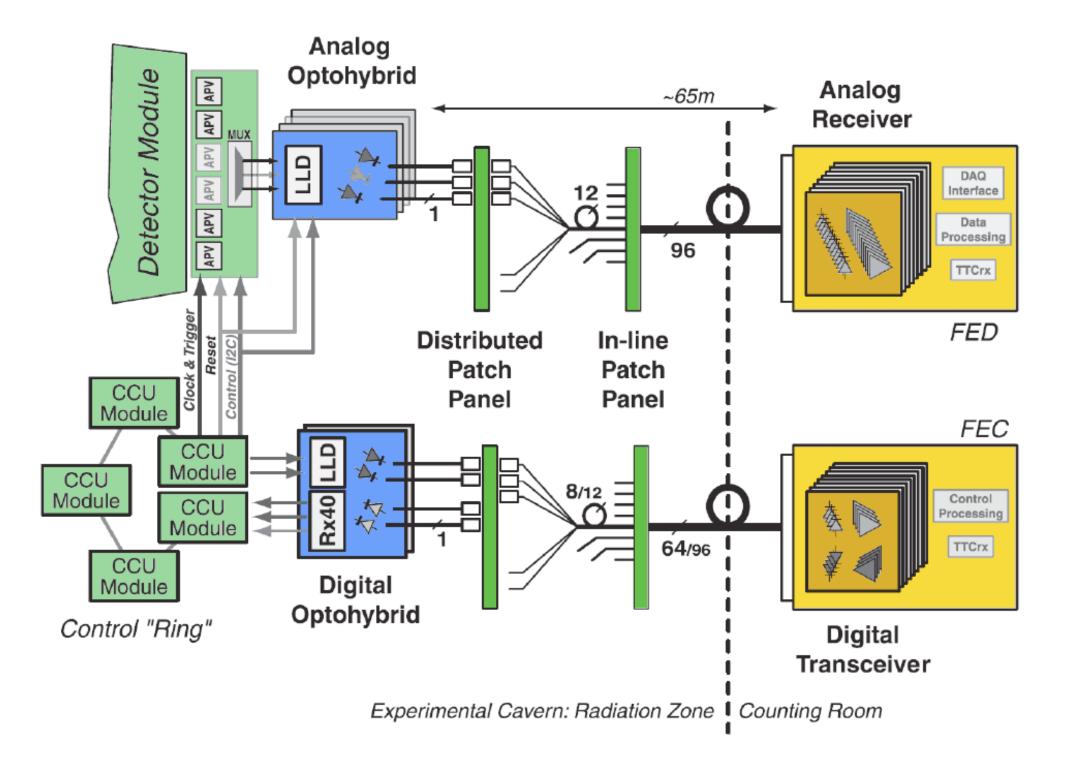
Pixel DAQ and Control Overview





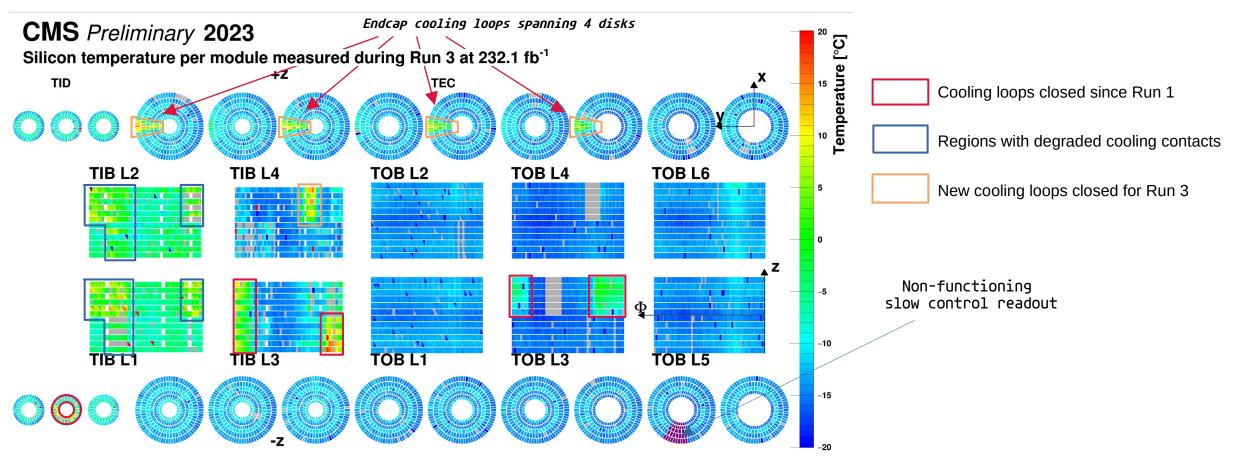
Strips DAQ and Control Overview





Strip Detector – Operational Status

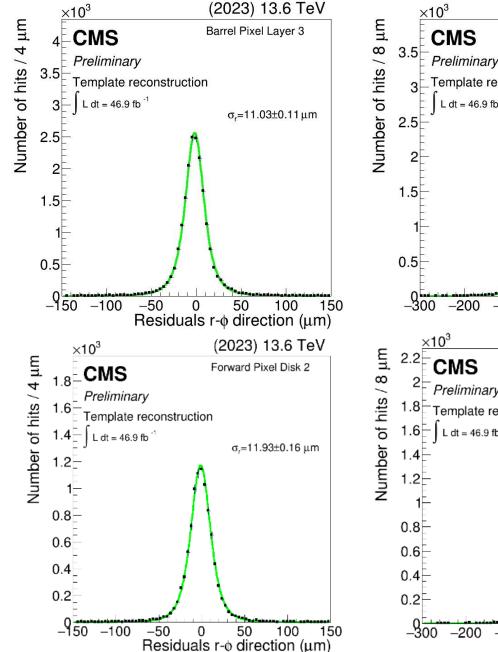


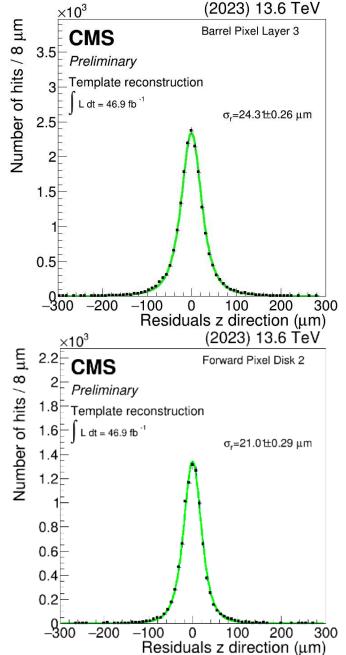


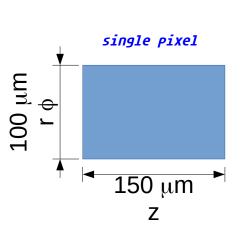
- Rather inhomogeneous temperature distribution to a number of (unfortunately well-known) issues
 - 5 out of 180 cooling loops closed since Run 1 (closed between 2009 and 2011)
 - Regions with degraded cooling contacts since 2009 overpressure incident especially in TIB layers 1 and 2
- 2 more cooling loops had to be closed towards the end of LS2

Pixel – Hit resolution



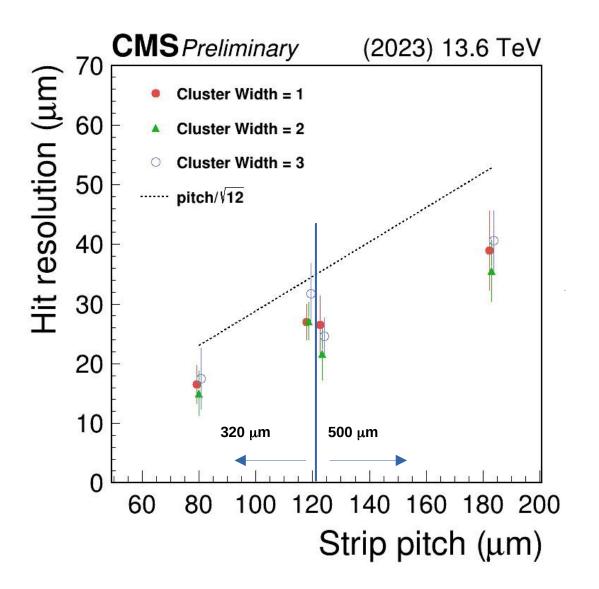




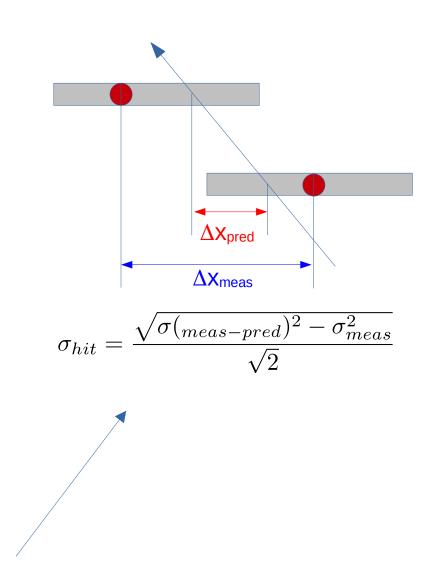


- Hit resolution measured for layers other than layer 1 and 4 (disks 1 and 3) to have good pointing resolution from surrounding layers
- Position estimate via "template" method → precise simulation of charge distribution inside sensitive volume and readout response
 - Excellent resolution in both $r\phi$ and z

Strips – Hit Resolution



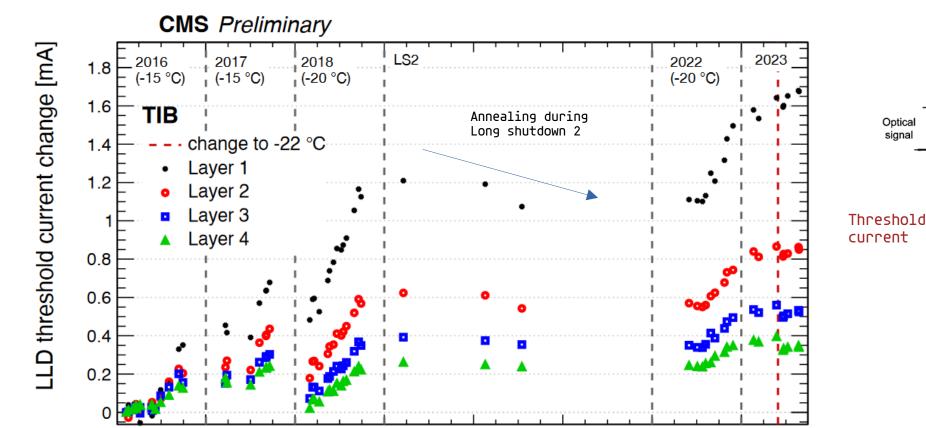


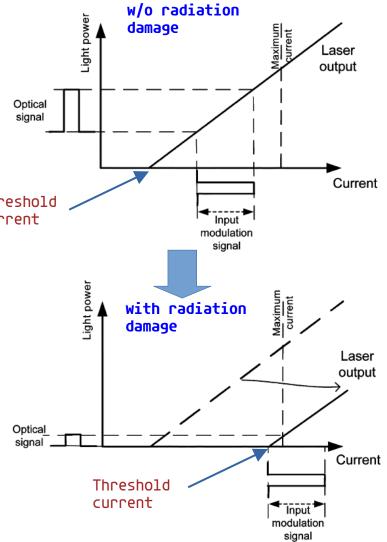


- Measured in with "pair method" by using hits from overlapping modules in the same layer
 - Significantly better than binary resolution in all layers
 - N.B. strip reconstruction only uses center-of-gravity, not charge (sharing) templates

Strips Laser Driver Threshold Currents







• Laser driver threshold current monitored regularly

2019

- Affected by radiation damage and annealing but also temperature
- Clear dependence on radius can be seen

2018

• Temperature set point changes manifest as drops in the distribution

2020

2021

2022

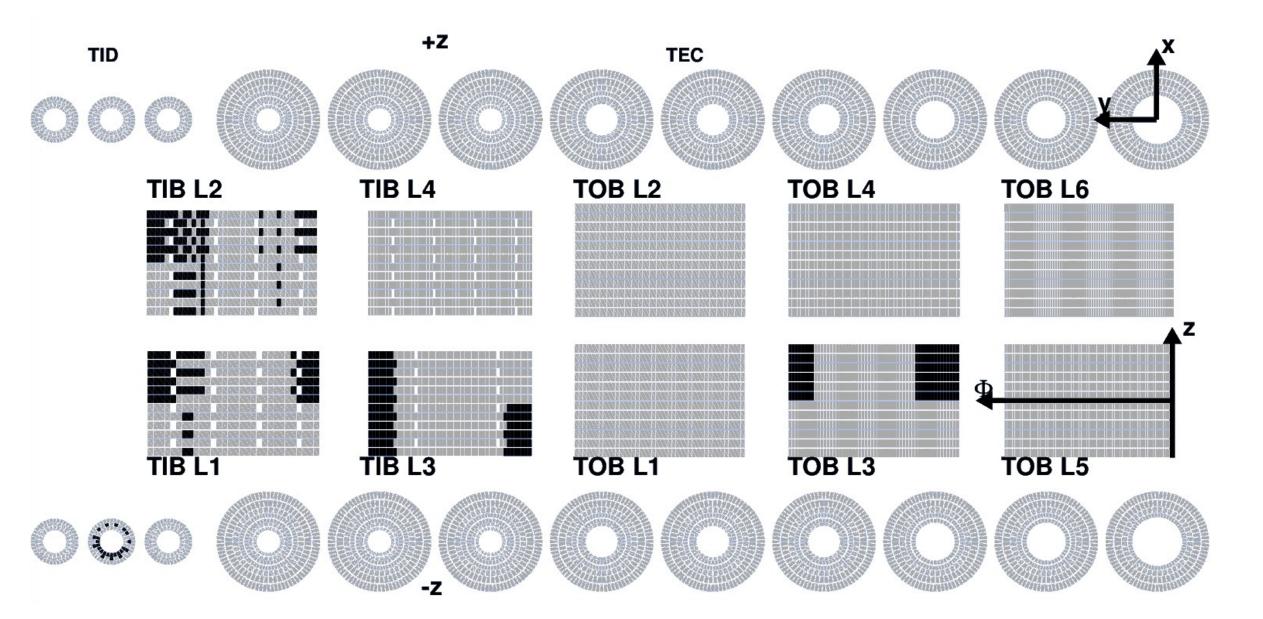
2023

• Ample margin until end-of-life of Strip Tracker

2017

Strips Bad Components – Expectation from 2012





TDR of Phase-1 Pixel Detector, 2012: modules in black that are expected to degrade in performance in the future